



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q67726

Mitsuo OSADA, et al.

Appln. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: Michael E. Lavilla

Filed: December 13, 2001

For:

MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC

PACKAGE USING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated August 24, 2005, please amend the aboveidentified application as follows on the accompanying pages. Amendment Under 37 CFR 1.111 U.S. Application No. 10/009,822

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

Registration No. 25,426

SUGHRUE MION, PLLC

Telephone: (202) 293-7060

Facsimile: (202) 293-7860

washington office 23373

CUSTOMER NUMBER

Date: November 23, 2005